

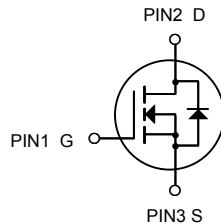
### DESCRIPTION

Third Generation HEXFETs from international Rectifier provide the designer with the best combination of fast switching, ruggedized device design, low on-resistance cost effectiveness.

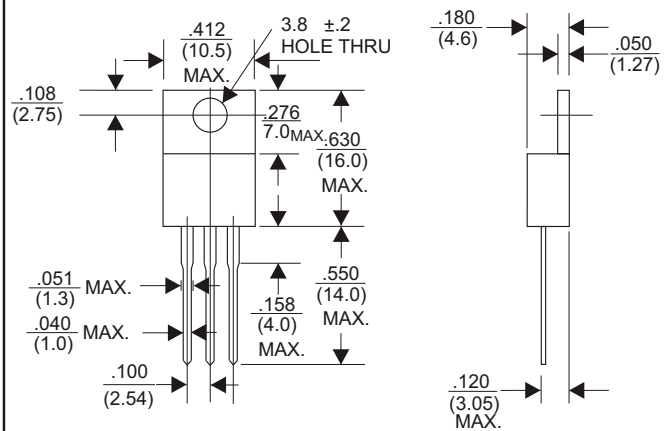
The TO-220-3L package is universally preferred for all commercial-industrial applications at power dissipation levels to approximately 50 watts. The low thermal resistance and low package cost of the TO-220-3L contribute to its wide acceptance throughout the industry.

### FEATURE

- Repetitive Avalanche Rated
- Fast Switching
- Ease of Paralleling
- Simple Drive Requirement



### TO-220AB



### MAXIMUM RATINGS (T<sub>a</sub>=25°C unless otherwise noted)

Symbol	Parameter	Value	Units
I <sub>D</sub>	Continuous Drain Current, V <sub>GS</sub> @ 10 V	18	A
P <sub>D</sub>	Power Dissipation	2	W
	Linear Derating Factor	1.0	W/°C
V <sub>GS</sub>	Gate-Source Voltage	±20	V
E <sub>AS</sub>	Single Pulse Avalanche Energy (note 1)	580	mJ
R <sub>θJA</sub>	Thermal Resistance from Junction to Ambient	62.5	°C/W
T <sub>J</sub>	Junction Temperature	150	°C
T <sub>STG</sub>	Storage Temperature	-55~+150	°C

# IRF640

## ELECTRICAL CHARACTERISTICS ( $T_a=25^\circ\text{C}$ unless otherwise specified)

Parameter	Symbol	Test conditions	Min	Typ	Max	Unit
Drain-source breakdown voltage	$V_{(BR)DSS}$	$V_{GS}=0V, I_D=250\mu A$	200			V
Gate-threshold voltage	$V_{(GS)th}$	$V_{DS}=V_{GS}, I_D=250\mu A$	2		4	
Gate-body leakage	$I_{GSS}$	$V_{DS}=0V, V_{GS}=\pm 20V$			$\pm 100$	nA
Zero gate voltage drain current	$I_{DSS}$	$V_{DS}=200V, V_{GS}=0V$			25	$\mu A$
Drain-source on-resistance (note 2)	$R_{DS(on)}$	$V_{GS}=10V, I_D=11A$		0.125	0.18	$\Omega$
Forward transconductance (note 2)	$g_{fs}$	$V_{DS}=50V, I_D=11A$	6.7			S
Diode forward voltage (note 2)	$V_{SD}$	$I_S=18A, V_{GS}=0V$			2	V
Input capacitance (note 3)	$C_{iss}$	$V_{DS}=25V, V_{GS}=0V, f=1MHz$		1300		pF
Output capacitance (note 3)	$C_{oss}$			400		
Reverse transfer capacitance (note 3)	$C_{riss}$			120		
Turn-on time (note 2,3)	$t_{d(on)}$	$V_{DD}=100V, R_D=5.4\Omega, I_D=18A, R_G=9.1\Omega$		14		ns
Rise time	$t_r$			51		
Turn-off time (note 2,3)	$t_{d(off)}$			45		
Fall time (note 2,3)	$t_f$			36		

### Notes:

- $V_{DD}=50V$ , starting  $T_J=25^\circ\text{C}$ ,  $L=2.7mH, R_G=25\Omega, I_{AS}=18A$ .
- Pulse test: Pulse width  $\leq 300\mu s$ , duty cycle  $\leq 2\%$ .
- These parameters have no way to verify.

## RATING AND CHARACTERISTIC CURVES (IRF640 )

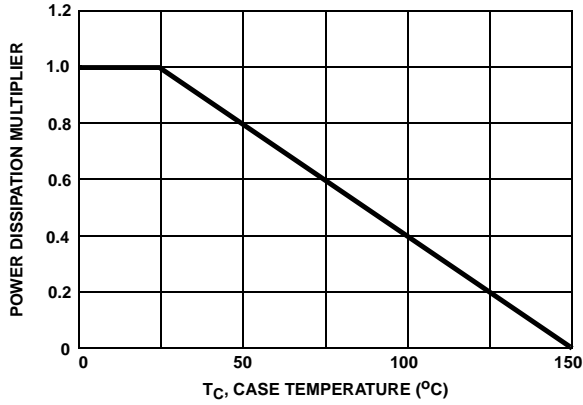


FIGURE 1. NORMALIZED POWER DISSIPATION vs CASE TEMPERATURE

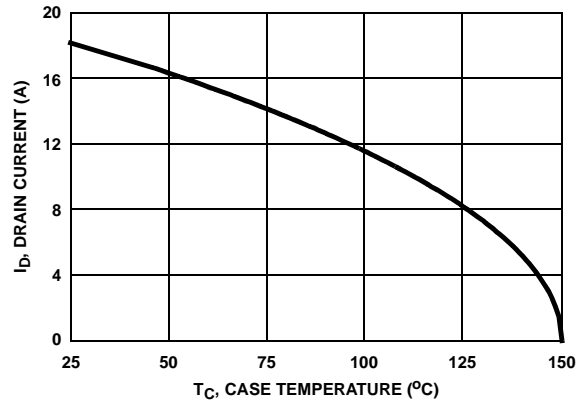


FIGURE 2. MAXIMUM CONTINUOUS DRAIN CURRENT vs CASE TEMPERATURE

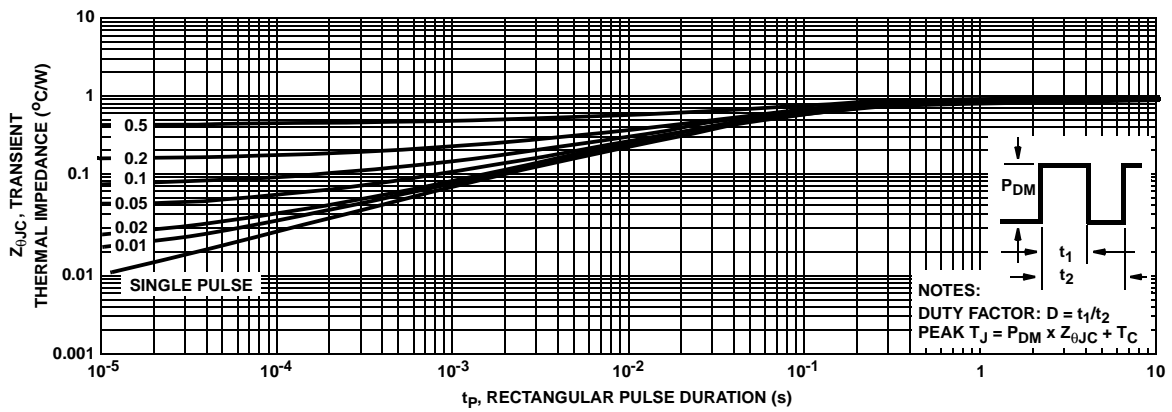


FIGURE 3. MAXIMUM TRANSIENT THERMAL IMPEDANCE

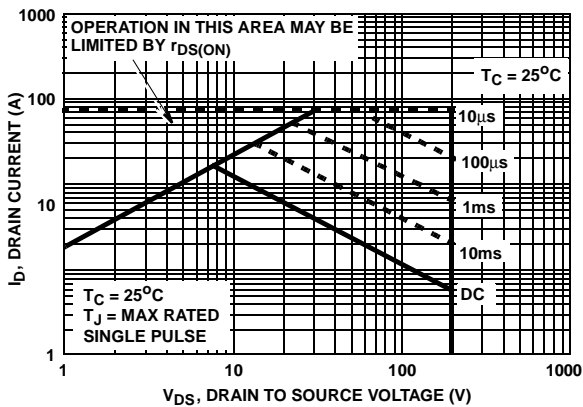


FIGURE 4. FORWARD BIAS SAFE OPERATING AREA

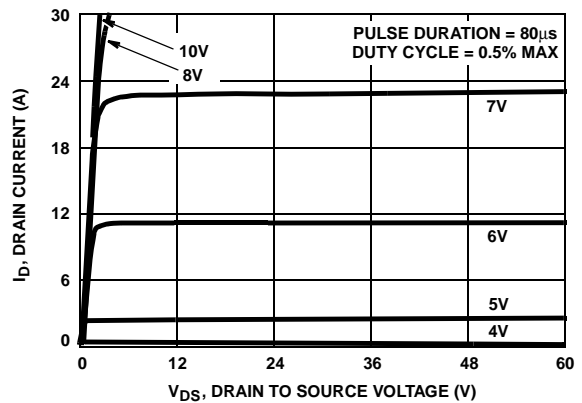


FIGURE 5. OUTPUT CHARACTERISTICS

## RATING AND CHARACTERISTIC CURVES (IRF640 )

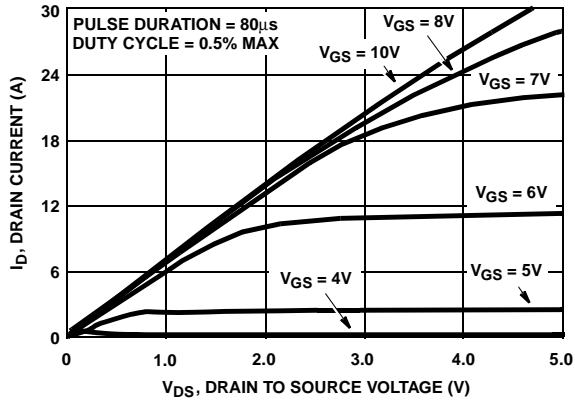


FIGURE 6. SATURATION CHARACTERISTICS

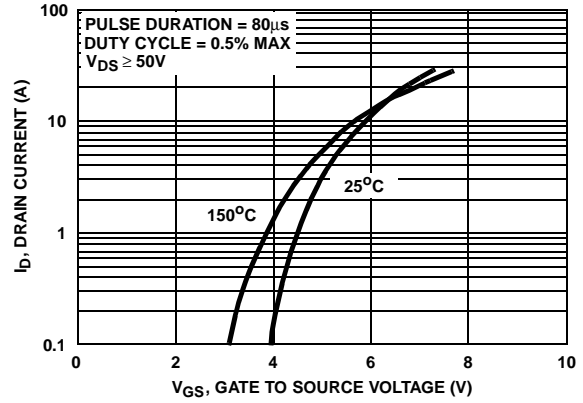


FIGURE 7. TRANSFER CHARACTERISTICS

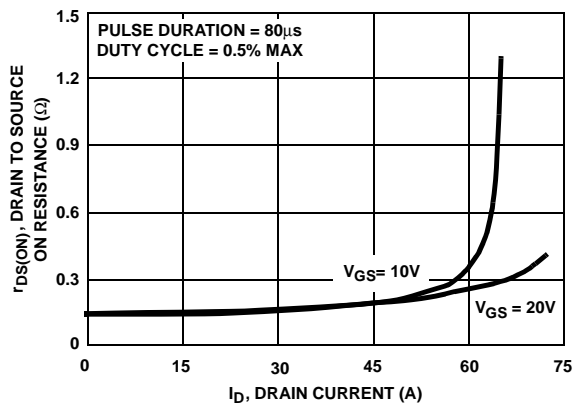


FIGURE 8. DRAIN TO SOURCE ON RESISTANCE vs GATE VOLTAGE AND DRAIN CURRENT

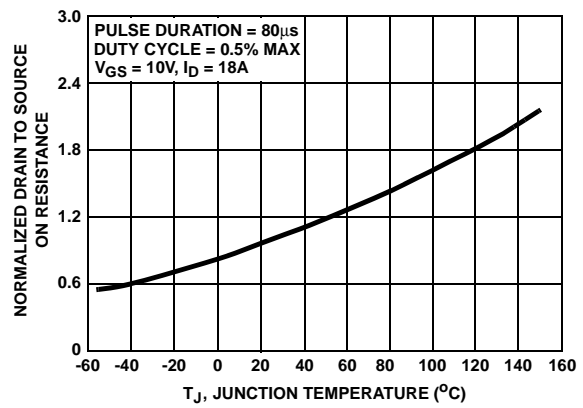


FIGURE 9. NORMALIZED DRAIN TO SOURCE ON RESISTANCE vs JUNCTION TEMPERATURE

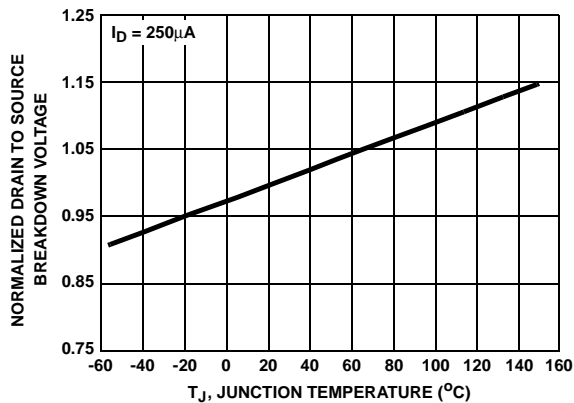


FIGURE 10. NORMALIZED DRAIN TO SOURCE BREAKDOWN VOLTAGE vs JUNCTION TEMPERATURE

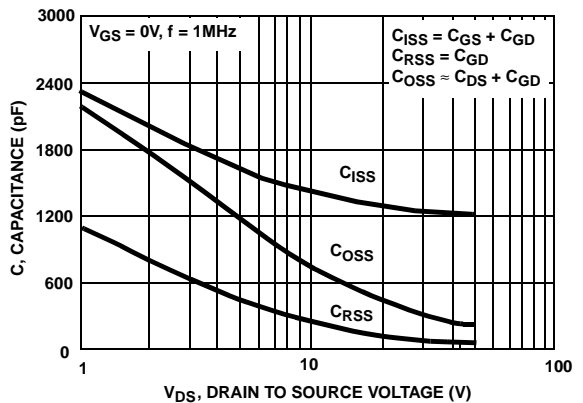


FIGURE 11. CAPACITANCE vs DRAIN TO SOURCE VOLTAGE

## RATING AND CHARACTERISTIC CURVES (IRF640 )

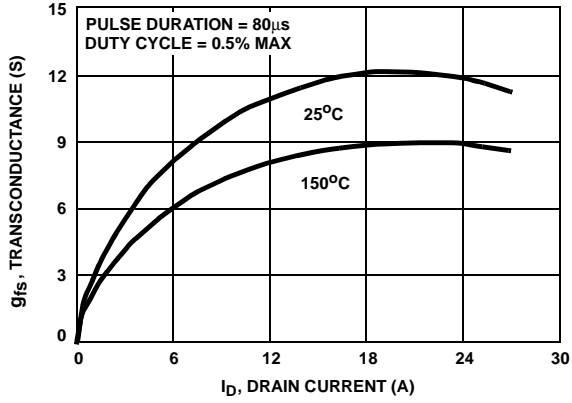


FIGURE 12. TRANSCONDUCTANCE vs DRAIN CURRENT

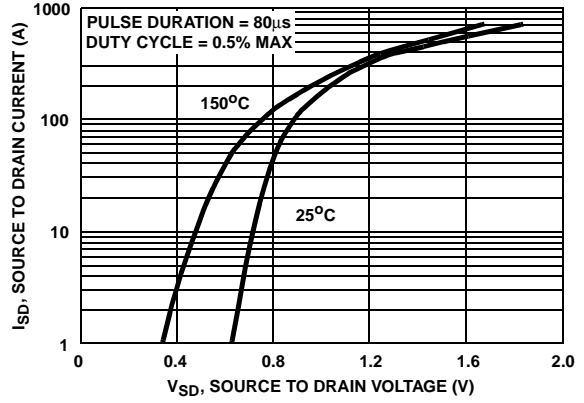


FIGURE 13. SOURCE TO DRAIN DIODE VOLTAGE

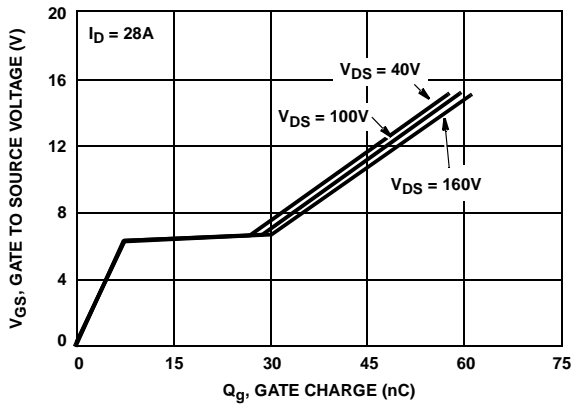


FIGURE 14. GATE TO SOURCE VOLTAGE vs GATE CHARGE